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PATENT

Docket No. 420099-654

LSI Logic No. P-2880/1D

I hereby certify that this correspondence and the attachment are being deposited with the United States Postal Service as First Class Mail on February 12, 1998, in an envelope addressed to: Honorable Commissioner of Patents and Trademarks, Washington, D.C., 20231.

*Cheryle A. Healion*  
Cheryle A. Healion

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FEB 24 1998

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application Of:

MIKE LIANG

Serial Number: 08/909,312

Filing Date: August 14, 1997

Entitled: **METHOD FOR DISTRIBUTING  
CONNECTION PADS ON A  
SEMICONDUCTOR DIE  
(AS AMENDED)**

RECEIVED

APR 06 1998

GROUP 2200

Group Art Unit: 1104

Examiner:

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

**SECOND SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Sir:

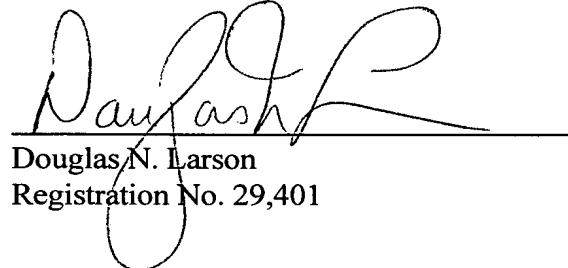
Submitted herewith are one sheet of Form PTO-1449 and one copy of each of the patent documents listed therein for the above-captioned divisional application.

It is respectfully requested that the Examiner make his consideration of these documents formally of record with his initial action.

PATENT  
Docket No. 420099-654  
LSI Logic No. P-2880/1D

If any fees are due with this Second Supplemental Information Disclosure Statement, the Commissioner is authorized to charge them to Deposit Account Number 16-2230.

Respectfully submitted,

  
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Douglas N. Larson  
Registration No. 29,401

Dated: February 12, 1998

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